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Application ID:

10774194

Title of Invention:

METHOD AND APPARATUS FOR INFILM DEFECT REDUCTION FOR

ELECTROCHEMICAL COPPER ·

DEPOSITION

First Named Inventor:

YI-CHIAU HUANG

Domestic/Foreign Application:

Domestic Application

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Statement

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6951

Attorney Docket Number:

AMAT8461

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TRANSMITTAL

Electronic Version v1.1 Stylesheet Version v1.1.0

> Title of Invention

METHOD AND APPARATUS FOR INFILM DEFECT REDUCTION FOR ELECTROCHEMICAL COPPER DEPOSITION

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Submitted by:	Elec. Sign.	Sign. Capacity
Mr. N. ALEXANDER NOLTE Registered Number: 45689	[N. ALEXANDER NOLTE]	Attorney

Documents being submitted

Files

us-ids

AMAT8461NAN-usidst.xml

us-ids.dtd

us-ids.xsl

Comments

NO FEES DUE - FILED BEFORE 1ST OA

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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18 Stylesheet Version v18.0

> Title of Invention

METHOD AND APPARATUS FOR INFILM DEFECT REDUCTION FOR ELECTROCHEMICAL COPPER DEPOSITION

Application Number:

10/774194

Confirmation Number:

6951

First Named Applicant:

YI-CHIAU HUANG

Attorney Docket Number: AMAT8461

Art Unit:

2812

Search string:

(4557785 or 5022419 or 5095027 or 5154199 or 5221360 or 5409310 or 6039059 or 6062239 or 6167893 or 6199298 or 6200876 or 6217667 or 6240933 or 6286231 or 6295999 or 6309981 or 6318385 or 6319728 or 6319841 or 6333275 or 6350319 or 6357142 or 6401732 or 6413436 or 6446643 or 6446644 or 6463938 or 6537416 or 6547660 or 6550484 or 6558053 or 6558478 or 6569696 or 6615854 or 6684891 or 6722557

or 20020026729).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20020026729	2002-03-07	BERGMAN, ET AL.			

Remarks

Note: Remarks are not for responding to an office action.

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